2SB831

Silicon PNP Epitaxial

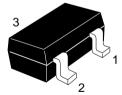
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Application

- Low frequency amplifier
- Complementary pair with 2SD1101

Outline

MPAK



- 1. Emitter
- 2. Base
- 3. Collector



2SB831

Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

Item	Symbol	Ratings	Unit
Collector to base voltage	V_{CBO}	– 25	V
Collector to emitter voltage	V _{CEO}	-20	V
Emitter to base voltage	V _{EBO}	– 5	V
Collector current	I _c	-0.7	A
Collector peak current	i _{C(peak)}	– 1	A
Collector power dissipation	P _c	150	mW
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

Electrical Characteristics (Ta = 25°C)

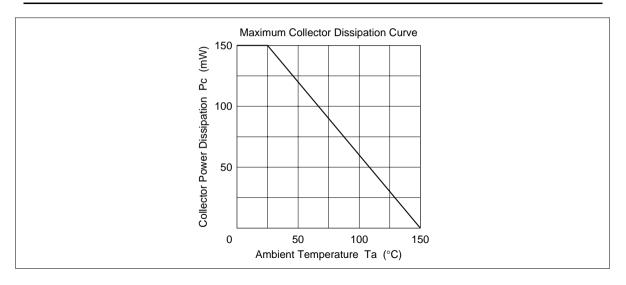
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	-25	_	_	V	$I_{c} = -10 \ \mu A, \ I_{E} = 0$
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	-20	_	_	V	$I_{C} = -1 \text{ mA}, R_{BE} = \infty$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	- 5	_	_	V	$I_{E} = -10 \ \mu\text{A}, \ I_{C} = 0$
Collector cutoff current	I _{CBO}	_	_	-1.0	μΑ	$V_{CB} = -20 \text{ V}, I_{E} = 0$
DC current transfer ratio	h _{FE} *1	85	_	240		$V_{CE} = -1 \text{ V}, I_{C} = -0.15 \text{ A}^{*2}$
Collector to emitter saturation voltage	$V_{\text{CE(sat)}}$	_	_	-0.5	V	$I_{\rm C} = -0.5 \text{ A}, I_{\rm B} = -0.05 \text{ A}^{*2}$
Base to emitter voltage	V_{BE}	_	_	-1.0	V	$V_{CE} = -1 \text{ V}, I_{C} = -0.15 \text{ A}^{*2}$

Notes: 1. The 2SB831 is grouped by $h_{\rm FE}$ as follows.

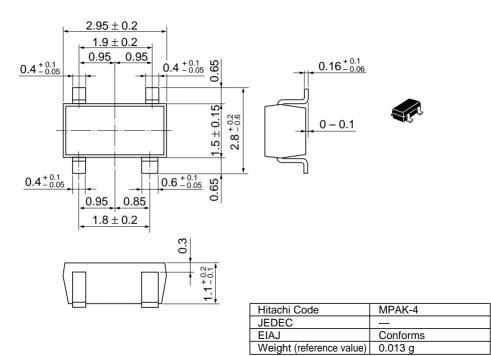
2. Pulse test

Grade	В	С
Mark	BB	ВС
h _{FE}	85 to 170	120 to 240

See characteristic curves of 2SB561.



Unit: mm



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